

H&M502

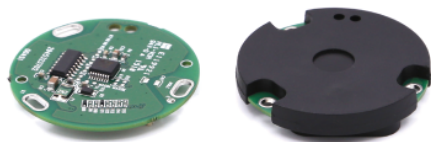
KÖNIG
康尼格

Dual-station Low Pressure Molding Machine

低压注塑设备(双工位)

适用于低压注塑热熔胶材料对电子元器件注塑封装保护，为敏感电子元器件，如：PCB/FPC，传感器，连接器，线束，电池等，提供更优的封装保护。

The machines are engineered for Low Pressure Injection Molding applications. Using hot-melt adhesive material to protect delicate electronic components, such as PCB/FPC, sensors, connectors, wiring harness, batteries, etc.



特点

- 注胶系统采用高可靠性的齿轮泵和注胶枪，结构紧凑注胶精准稳定。
- 设备分段控温，胶缸、胶管和胶枪均可独立控制，温度控制精准。
- 注胶参数通过PLC控制，注胶压力通过面板压力阀进行调节，操作简便。
- 操作台和熔胶系统采用分体布局，使用灵活。
- 操作台设有产品顶出装置，方便取出产品。
- 工作保护采用双手同时启动按钮，同时配备安全光栅。
- 采用标准模架设计，实现快速换模。
- 设备采用模块化设计，便于维护和保养，使用寿命长。

FEATURES

- Injection system using high reliability gear pump and glue guns, the injection is precise and stable with compact structure.
- The cylinder, hose and gun can be controlled independently, and the temperature control is accurate.
- The injection parameters are controlled by PLC system; Injecting pressure is easy to adjust through the control panel.
- Work station and melt system adopts fission layout and uses flexible.
- The operating table is equipped with an ejection device to facilitate the removal of products.
- Working protection uses two-hands start button, also with infrared safety grating
- With standard mold design to realize rapid die change.
- The equipment adopts modular design, which is easy to maintain.

双工位 | 双枪侧式注胶 可选配双胶缸 | 注胶更稳定
更大的模具应用空间 | 适合复杂的多模穴和滑块机构的模具

Dual-station, side injection with two nozzles. Optional double melt system, more stable injection, higher productivity. Larger application space for molds, suitable for complex mold with multi cavities and slide mechanisms



低压注塑工艺 Low Pressure Injection Molding



150~200°C
极低的注塑温度



1.5~60bar
极低的注塑压力



1S
成型速度快至1s



IP67
防水防尘

以上数据取决于具体产品，可能存在变化
Characters depend on project.

H&M502

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Dual-station Higher Productivity

双工位 | 生产效率更高

熔胶系统与数量 Melting Tank Model&Q'ty	KH05(5 Liter)×1PC
注胶枪型号与数量角度 Nozzle&Tip Angle	KG40×2PC(36°)
注胶管型号与数量 Heated Hose Model&Q'ty	KJ16×2PC
输入电压 Electricity	220VAC/1Phase/50 or 60Hz
用气量 Air Consumption	0.1 m³/min
温控分区 Temperature Control Zones	5
最高设定温度 Max. Setting Temperature	up to 250°C
最大功率 Max. Power	4.5Kw
最低工作气压 Min. Air Pressure	0.5Mpa
合模方式 Clamping Device	气缸(Cylinder)
合模压力 Clamping Force	Max.1.2Ton
合模行程 Clamping Stroke (mm)	150mm
标准模具尺寸 Standard Mold Size(mm)	190×130×150
最大模具尺寸 Max. Mold Size(mm)	300×200×150
控制系统 Control System	PLC+7" HMI
工作台高度 Work Station Height(mm)	1030
机台尺寸重量 Machine Size(mm)	1080×1890×718 (440Kgs)
包装尺寸重量 Packing Size(mm)	1280×2000×920 (490Kgs)

高生产效率
High Efficiency



低温低压，成型快速，无损敏感
电子元器件

Perfect protect sensitive
electronic components with
low temperature & low pressure

高产品良率
High Yield



模具成型，高一致性，培训简单
操作便捷

High consistency with mold
forming, easy to operate

节约材料
Save Material



无需灌封外壳，无需多次操作，
一次快速成型

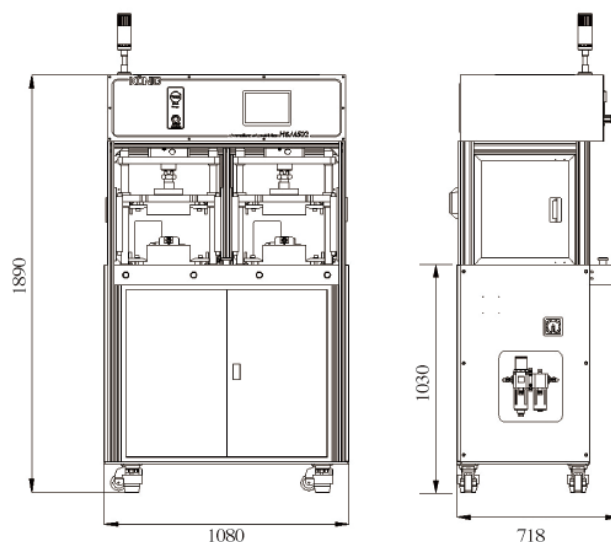
No need plastic shell, no need to
operate many times

和谐生产环境
ECO Friendly



生产过程中无有毒烟气产生，无
化学反应

No toxic smoke during
production process



可选设备
Optional Equipment

☐ 材料干燥机
Material dryer

☐ 冷水机
Water chillers

☐ 上下料机械手
Loading manipulators

☐ 自动加料系统
Automatic feeding system

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